

TITLE: Microelectronic Die Providing Improved Heat Dissipation and Method of Packaging Same  
INVENTOR(S): Crippen  
DOCKET NO.: P12659

### REPLACEMENT SHEET

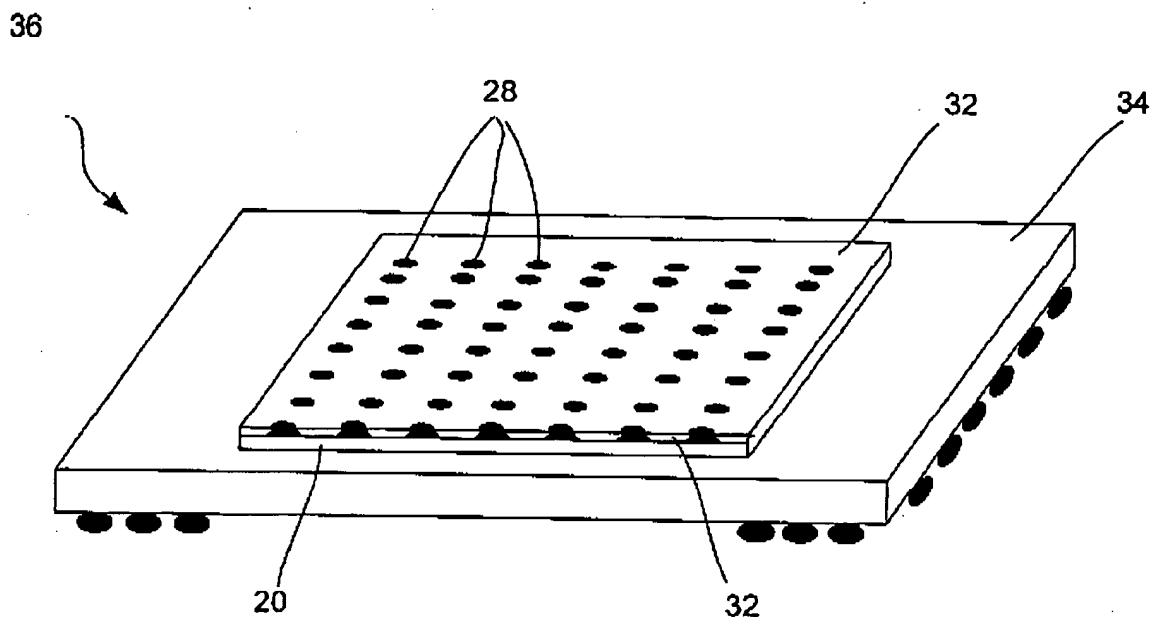


Fig. 8

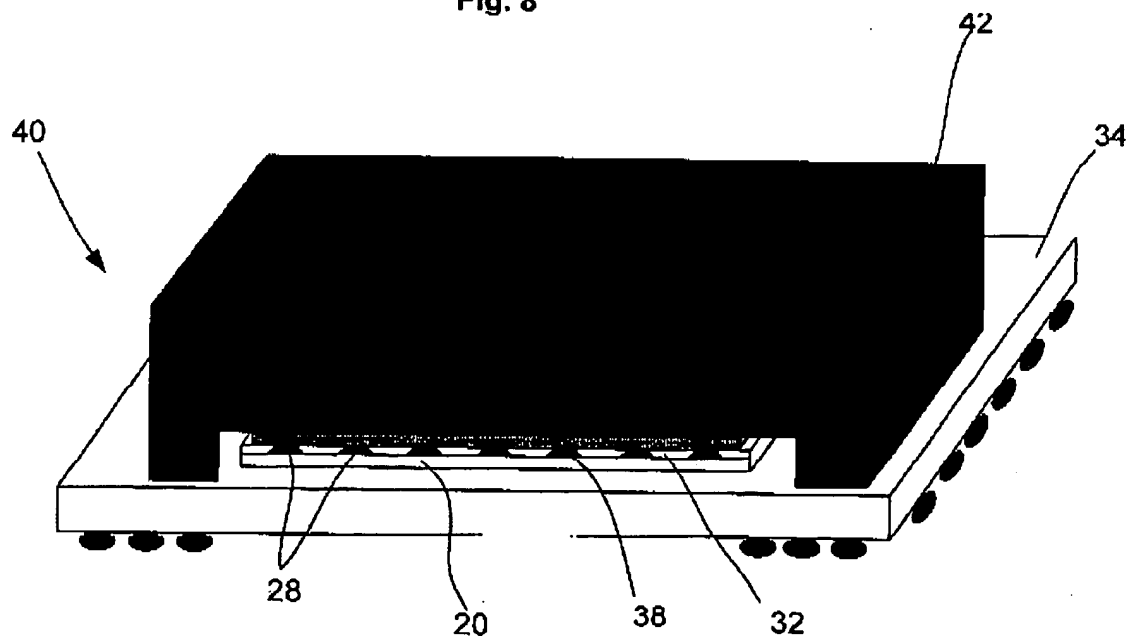


Fig. 9